

Carrier with Metal Bumps for Semiconductor Die Packages

ABSTRACT OF THE DISCLOSURE

A carrier for a semiconductor die package is disclosed. In one embodiment, the carrier includes a metal layer and a plurality of bumps formed in the metal layer. The
5 bumps can be formed by stamping.

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(1)
(2)
(3)
(4)
(5)
(6)
(7)

4
(1)
(2)
(3)
4a
4b
4c
4d
4e
4f